L Number	Hits	Search Text	DB	Time stamp
1	80380	340/$.ccls.	USPAT	2004/01/07 13:56
2	2591	tamper adj1 resistant	USPAT	2004/01/07 13:56
3	188	340/$.ccls. and (tamper adj1 resistant)	USPAT	2004/01/07 14:00
4	100	235/$.ccls. and tamper adj1 resistant	USPAT	2004/01/07 14:03
5	2776	713/184.ccls. or 713/185.ccls. or 713/189.ccls. or 713/192.ccls. or 713/194.ccls. or 713/200-202.ccls.	USPAT	2004/01/07 14:05
6	579	705/41-44.ccls.	USPAT	2004/01/07 14:05
7	218	705/64-65.ccls.	USPAT	2004/01/07 14:05
8	331	340/687.ccls.	USPAT	2004/01/07 14:06
9	80380	340/$.ccls.	USPAT	2004/01/07 14:06
10	4703	235/492.ccls. or 235/380.ccls. or 235/487.ccls. or 235/435.ccls. or 235/462.25	USPAT	2004/01/07 14:07
11	87579	(235/$.ccls. and tamper adj1 resistant) or (713/184.ccls. or 713/185.ccls. or 713/189.ccls. or 713/192.ccls. or 713/194.ccls. or 713/200-202.ccls.) or 705/41-44.ccls. or 705/64-65.ccls. or 340/687.ccls. or 340/$.ccls. or (235/492.ccls. or 235/380.ccls. or 235/487.ccls. or 235/435.ccls. or 235/462.25)	USPAT	2004/01/07 14:07
12	11758	encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3	USPAT; EPO; JPO	2004/01/07 14:08
13	859	(encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) and (display$4 and pad)	USPAT; EPO; JPO; DERWENT	2004/01/07 14:08
14	9	((encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) same pad) same touch near2 screen	USPAT; EPO; JPO; DERWENT	2004/01/07 14:08
15	4416	chip near2 glass	USPAT; EPO; JPO; DERWENT	2004/01/07 14:08
16	8	(touch near2 pad) and ((encrypt$4 or cipher$4 or encipher$4)near4 circuit)	USPAT; EPO; JPO; DERWENT	2004/01/07 14:09
17	37	(touch near2 screen and tamper adj1 resistant) and (PIN or key or password)	USPAT; EPO; JPO; DERWENT	2004/01/07 14:09
18	29	COG and ASIC	USPAT; EPO; JPO; DERWENT	2004/01/07 14:09
19	39	wire near2 technology near4 pad	USPAT; EPO; JPO; DERWENT	2004/01/07 14:09
20	230	ASIC same (encrypt$4 or cipher$4 or encipher$4)	USPAT; EPO; JPO; DERWENT	2004/01/07 14:15
21	82	(four adj2 wire)and (touch adj1 pad or touch adj1 screen)	USPAT; EPO; JPO; DERWENT	2004/01/07 14:13
22	199	380/227-229.ccls.	USPAT	2004/01/07 14:13
23	329	380/227-229.ccls. or 380/239.ccls.	USPAT	2004/01/07 14:14
24	10139	touch adj2 screen	USPAT	2004/01/07 14:15
25	3	(touch adj2 screen) and (COG and ASIC)	USPAT	2004/01/07 14:15

26	7	silicon near2 circuit and tamper adj2 resistant	USPAT	2004/01/07 14:18
-	1	("5475377").PN.	USPAT	2004/01/06 11:09
-	7590	encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3	USPAT	2004/01/07 14:08
-	43789	display$4 and pad	USPAT	2004/01/06 11:11
-	850	(encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) and (display$4 and pad)	USPAT	2004/01/07 14:08
-	194	(encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) same pad	USPAT	2004/01/06 11:14
-	7	((encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) same pad) same touch near2 screen	USPAT	2004/01/07 14:08
-	3836	touch near2 pad	USPAT	2004/01/06 11:20
-	1183	(encrypt$4 or cipher$4 or encipher$4)near4 circuit	USPAT	2004/01/06 11:21
-	6	((encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) and ((encrypt$4 or cipher$4 or encipher$4)near4 circuit)) and (touch near2 pad)	USPAT	2004/01/06 11:24
-	7	(touch near2 pad) and ((encrypt$4 or cipher$4 or encipher$4)near4 circuit)	USPAT	2004/01/07 14:09
-	95	(encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) and (touch near2 pad)	USPAT	2004/01/06 11:26
-	6	((encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) and (touch near2 pad)) and ((encrypt$4 or cipher$4 or encipher$4)near4 circuit)	USPAT	2004/01/06 11:26
-	813	(encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) and ((encrypt$4 or cipher$4 or encipher$4)near4 circuit)	USPAT	2004/01/06 12:37
-	675	tamper near2 detect$4	USPAT	2004/01/06 12:51
-	0	n adj1 wire adj1 technology	USPAT	2004/01/06 13:28
-	0	"4" adj1 wire adj1 technology	USPAT	2004/01/06 13:29
-	3	four adj1 wire adj1 technology	USPAT	2004/01/06 13:29
-	0	wire adj1 technology adj1 pad	USPAT	2004/01/06 13:36
-	91	touch adj1 pad same wire	USPAT	2004/01/06 13:39
-	9174	four adj2 wire	USPAT	2004/01/06 13:39
-	2634	touch adj1 pad	USPAT	2004/01/06 13:40
-	0	(four adj2 wire) same (touch adj1 pad)	USPAT	2004/01/06 13:42
-	634	touch near2 screen and ASIC	USPAT	2004/01/06 13:42
-	2634	touch adj1 pad	USPAT	2004/01/06 13:43
-	54	(touch near2 screen and ASIC) and (touch adj1 pad)	USPAT	2004/01/06 13:45
-	0	chip adj1 on adj1 glass	USPAT	2004/01/06 13:48
-	1147	chip adj1 glass	USPAT	2004/01/06 13:46
-	0	(chip adj1 glass) and ((touch near2 screen and ASIC) and (touch adj1 pad))	USPAT	2004/01/06 13:46

-	0	(chip adj1 glass) and (touch near2 screen and ASIC)	USPAT	2004/01/06 13:46
-	0	(chip adj1 glass) and (touch adj1 pad)	USPAT	2004/01/06 13:46
-	2992	chip near2 glass	USPAT	2004/01/07 14:08
-	0	(chip near2 glass) and ((touch near2 screen and ASIC) and (touch adj1 pad))	USPAT	2004/01/06 13:46
-	0	(chip near2 glass) and (touch adj1 pad)	USPAT	2004/01/06 13:46
-	0	(chip near2 glass) and (touch near2 screen and ASIC)	USPAT	2004/01/06 13:48
-	0	chip near1 on near1 glass	USPAT	2004/01/06 13:48
-	0	chip near2 glass and (touch adj1 pad)	USPAT	2004/01/06 13:54
-	23	COG near2 technology	USPAT	2004/01/07 07:42
-	0	COG and temper near2 resistant	USPAT	2004/01/06 15:18
-	4	COG and tamper near2 resistant	USPAT	2004/01/06 15:18
-	0	touch near2 screen and ASIX and tamper adj1 resistant	USPAT	2004/01/07 07:42
-	1	touch near2 screen and ASIC and tamper adj1 resistant	USPAT	2004/01/07 07:43
-	43	touch near2 screen and tamper adj1 resistant	USPAT	2004/01/07 07:43
-	783961	PIN or key or password	USPAT	2004/01/07 07:43
-	36	(touch near2 screen and tamper adj1 resistant) and (PIN or key or password)	USPAT	2004/01/07 14:09
-	29	COG and ASIC	USPAT	2004/01/07 14:09
-	17447	encrypt$4 or cipher$4 or encipher$4	USPAT	2004/01/07 14:04
-	1118	ASIC and (encrypt$4 or cipher$4 or encipher$4)	USPAT	2004/01/07 10:01
-	218	ASIC same (encrypt$4 or cipher$4 or encipher$4)	USPAT	2004/01/07 14:10
-	826	(encrypt$4 or cipher$4 or encipher$4)near2 circuit	USPAT	2004/01/07 10:02
-	83	((encrypt$4 or cipher$4 or encipher$4)near2 circuit) and ASIC	USPAT	2004/01/07 10:24
-	37	wire near2 technology near4 pad	USPAT	2004/01/07 14:09
-	3848	(n near2wire near2 technology) and (touch adj1 pad or touch adj1 screen)	USPAT	2004/01/07 10:31
-	5733	(four near2wire near2 technology) and (touch adj1 pad or touch adj1 screen)	USPAT	2004/01/07 14:18
-	0	(four adj2 wire adj3 technology)and (touch adj1 pad or touch adj1 screen)	USPAT	2004/01/07 10:49
-	77	(four adj2 wire)and (touch adj1 pad or touch adj1 screen)	USPAT	2004/01/07 14:10
-	0	(four adj2 wire)and (seven adj2 wire) and (touch adj1 pad or touch adj1 screen)	USPAT	2004/01/07 10:52
-	1	(seven adj2 wire) and (touch adj1 pad or touch adj1 screen)	USPAT	2004/01/07 10:52

L Number	Hits	Search Text	DB	Time stamp
1	80380	340/$.ccls.	USPAT	2004/01/07 13:56
2	2591	tamper adj1 resistant	USPAT	2004/01/07 13:56
3	188	340/$.ccls. and (tamper adj1 resistant)	USPAT	2004/01/07 14:00
4	100	235/$.ccls. and tamper adj1 resistant	USPAT	2004/01/07 14:03
5	2776	713/184.ccls. or 713/185.ccls. or 713/189.ccls. or 713/192.ccls. or 713/194.ccls. or 713/200-202.ccls.	USPAT	2004/01/07 14:05
6	579	705/41-44.ccls.	USPAT	2004/01/07 14:05
7	218	705/64-65.ccls.	USPAT	2004/01/07 14:05
8	331	340/687.ccls.	USPAT	2004/01/07 14:06
9	80380	340/$.ccls.	USPAT	2004/01/07 14:06
10	4703	235/492.ccls. or 235/380.ccls. or 235/487.ccls. or 235/435.ccls. or 235/462.25	USPAT	2004/01/07 14:07
11	87579	(235/$.ccls. and tamper adj1 resistant) or (713/184.ccls. or 713/185.ccls. or 713/189.ccls. or 713/192.ccls. or 713/194.ccls. or 713/200-202.ccls.) or 705/41-44.ccls. or 705/64-65.ccls. or 340/687.ccls. or 340/$.ccls. or (235/492.ccls. or 235/380.ccls. or 235/487.ccls. or 235/435.ccls. or 235/462.25)	USPAT	2004/01/07 14:07
12	11758	encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3	USPAT; EPO; JPO	2004/01/07 14:08
13	859	(encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) and (display$4 and pad)	USPAT; EPO; JPO; DERWENT	2004/01/07 14:08
14	9	((encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) same pad) same touch near2 screen	USPAT; EPO; JPO; DERWENT	2004/01/07 14:08
15	4416	chip near2 glass	USPAT; EPO; JPO; DERWENT	2004/01/07 14:08
16	8	(touch near2 pad) and ((encrypt$4 or cipher$4 or encipher$4)near4 circuit)	USPAT; EPO; JPO; DERWENT	2004/01/07 14:09
17	37	(touch near2 screen and tamper adj1 resistant) and (PIN or key or password)	USPAT; EPO; JPO; DERWENT	2004/01/07 14:09
18	29	COG and ASIC	USPAT; EPO; JPO; DERWENT	2004/01/07 14:09
19	39	wire near2 technology near4 pad	USPAT; EPO; JPO; DERWENT	2004/01/07 14:09
20	230	ASIC same (encrypt$4 or cipher$4 or encipher$4)	USPAT; EPO; JPO; DERWENT	2004/01/07 14:10
21	82	(four adj2 wire)and (touch adj1 pad or touch adj1 screen)	USPAT; EPO; JPO; DERWENT	2004/01/07 14:10
-	1	("5475377").PN.	USPAT	2004/01/06 11:09
-	7590	encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3	USPAT	2004/01/07 14:08
-	43789	display$4 and pad	USPAT	2004/01/06 11:11
-	850	(encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) and (display$4 and pad)	USPAT	2004/01/07 14:08

–	194	(encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) same pad	USPAT	2004/01/06 11:14
–	7	((encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) same pad) same touch near2 screen	USPAT	2004/01/07 14:08
–	3836	touch near2 pad	USPAT	2004/01/06 11:20
–	1183	(encrypt$4 or cipher$4 or encipher$4)near4 circuit	USPAT	2004/01/06 11:21
–	6	((encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) and ((encrypt$4 or cipher$4 or encipher$4)near4 circuit)) and (touch near2 pad)	USPAT	2004/01/06 11:24
–	7	(touch near2 pad) and ((encrypt$4 or cipher$4 or encipher$4)near4 circuit)	USPAT	2004/01/07 14:09
–	95	(encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) and (touch near2 pad)	USPAT	2004/01/06 11:26
–	6	((encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) and (touch near2 pad)) and ((encrypt$4 or cipher$4 or encipher$4)near4 circuit)	USPAT	2004/01/06 11:26
–	813	(encrypt$4 or cipher$4 or encipher$4)near4(key or PIN or password$3) and ((encrypt$4 or cipher$4 or encipher$4)near4 circuit)	USPAT	2004/01/06 12:37
–	675	tamper near2 detect$4	USPAT	2004/01/06 12:51
–	0	n adj1 wire adj1 technology	USPAT	2004/01/06 13:28
–	0	"4" adj1 wire adj1 technology	USPAT	2004/01/06 13:29
–	3	four adj1 wire adj1 technology	USPAT	2004/01/06 13:29
–	0	wire adj1 technology adj1 pad	USPAT	2004/01/06 13:36
–	91	touch adj1 pad same wire	USPAT	2004/01/06 13:39
–	9174	four adj2 wire	USPAT	2004/01/06 13:39
–	2634	touch adj1 pad	USPAT	2004/01/06 13:40
–	0	(four adj2 wire) same (touch adj1 pad)	USPAT	2004/01/06 13:42
–	634	touch near2 screen and ASIC	USPAT	2004/01/06 13:42
–	2634	touch adj1 pad	USPAT	2004/01/06 13:43
–	54	(touch near2 screen and ASIC) and (touch adj1 pad)	USPAT	2004/01/06 13:45
–	0	chip adj1 on adj1 glass	USPAT	2004/01/06 13:48
–	1147	chip adj1 glass	USPAT	2004/01/06 13:46
–	0	(chip adj1 glass) and ((touch near2 screen and ASIC) and (touch adj1 pad))	USPAT	2004/01/06 13:46
–	0	(chip adj1 glass) and (touch near2 screen and ASIC)	USPAT	2004/01/06 13:46
–	0	(chip adj1 glass) and (touch adj1 pad)	USPAT	2004/01/06 13:46
–	2992	chip near2 glass	USPAT	2004/01/07 14:08
–	0	(chip near2 glass) and ((touch near2 screen and ASIC) and (touch adj1 pad))	USPAT	2004/01/06 13:46
–	0	(chip near2 glass) and (touch adj1 pad)	USPAT	2004/01/06 13:46
–	0	(chip near2 glass) and (touch near2 screen and ASIC)	USPAT	2004/01/06 13:48

-	0	chip near1 on near1 glass	USPAT	2004/01/06 13:48
-	0	chip near2 glass and (touch adj1 pad)	USPAT	2004/01/06 13:54
-	23	COG near2 technology	USPAT	2004/01/07 07:42
-	0	COG and temper near2 resistant	USPAT	2004/01/06 15:18
-	4	COG and tamper near2 resistant	USPAT	2004/01/06 15:18
-	0	touch near2 screen and ASIX and tamper adj1 resistant	USPAT	2004/01/07 07:42
-	1	touch near2 screen and ASIC and tamper adj1 resistant	USPAT	2004/01/07 07:43
-	43	touch near2 screen and tamper adj1 resistant	USPAT	2004/01/07 07:43
-	783961	PIN or key or password	USPAT	2004/01/07 07:43
-	36	(touch near2 screen and tamper adj1 resistant) and (PIN or key or password)	USPAT	2004/01/07 14:09
-	29	COG and ASIC	USPAT	2004/01/07 14:09
-	17447	encrypt$4 or cipher$4 or encipher$4	USPAT	2004/01/07 14:04
-	1118	ASIC and (encrypt$4 or cipher$4 or encipher$4)	USPAT	2004/01/07 10:01
-	218	ASIC same (encrypt$4 or cipher$4 or encipher$4)	USPAT	2004/01/07 14:10
-	826	(encrypt$4 or cipher$4 or encipher$4)near2 circuit	USPAT	2004/01/07 10:02
-	83	((encrypt$4 or cipher$4 or encipher$4)near2 circuit) and ASIC	USPAT	2004/01/07 10:24
-	37	wire near2 technology near4 pad	USPAT	2004/01/07 14:09
-	3848	(n near2wire near2 technology) and (touch adj1 pad or touch adj1 screen)	USPAT	2004/01/07 10:31
-	5733	(four near2wire near2 technology) and (touch adj1 pad or touch adj1 screen)	USPAT	2004/01/07 10:48
-	0	(four adj2 wire adj3 technology)and (touch adj1 pad or touch adj1 screen)	USPAT	2004/01/07 10:49
-	77	(four adj2 wire)and (touch adj1 pad or touch adj1 screen)	USPAT	2004/01/07 14:10
-	0	(four adj2 wire)and (seven adj2 wire) and (touch adj1 pad or touch adj1 screen)	USPAT	2004/01/07 10:52
-	1	(seven adj2 wire) and (touch adj1 pad or touch adj1 screen)	USPAT	2004/01/07 10:52

Status: Path 1 of [Dialog Information Services via Modem]

Status: Initializing TCP/IP using (UseTelnetProto 1 ServiceID dialog.com)
Trying 31060000009999...Open

DIALOG INFORMATION SERVICES
PLEASE LOGON:
 ******** HHHHHHHH SSSSSSSS?
Status: Signing onto Dialog
 ****
ENTER PASSWORD:
 ******** HHHHHHHH SSSSSSSS? ********
Welcome to DIALOG
Status: Connected

Dialog level 03.06.02D

Last logoff: 20dec03 08:59:28
Logon file405 07jan04 14:23:46
            *** ANNOUNCEMENT ***
                 ***
--File 654 - US published applications from March 15, 2001 to the
present are now online. Please see HELP NEWS 654 for details.

                 ***
--File 581 - The 2003 annual reload of Population Demographics is
complete. Please see Help News581 for details.

                 ***
--File 990 - NewsRoom now contains February 2003 to current records.
File 992 - NewsRoom 2003 archive has been newly created and contains
records from January 2003. The oldest months's records roll out of
File 990 and into File 992 on the first weekend of each month.
To search all 2003 records BEGIN 990, 992, or B NEWS2003, a new
OneSearch category.
                 ***
--Connect Time joins DialUnits as pricing options on Dialog.
See HELP CONNECT for information.
                 ***
                 ***
--SourceOne patents are now delivered to your email inbox
as PDF replacing TIFF delivery. See HELP SOURCE1 for more
information.
                 ***
--Important news for public and academic
libraries. See HELP LIBRARY for more information.
                 ***
--Important Notice to Freelance Authors--
See HELP FREELANCE for more information
                 ***
NEW FILES RELEASED
***DIOGENES: Adverse Drug Events Database (File 181)
***Emergency Room (File 454), Hospital Inpatient Profiles (File 462),
   and Hospital Outpatient Profiles (File 463)
***World News Connection (File 985)
***Dialog NewsRoom - 2003 Archive (File 992)
***TRADEMARKSCAN-Czech Republic (File 680)
***TRADEMARKSCAN-Hungary (File 681)
***TRADEMARKSCAN-Poland (File 682)
                 ***
UPDATING RESUMED
                 ***
RELOADED
***Population Demographics -(File 581)

***CLAIMS Citation (Files 220-222)

REMOVED
                              ***

        >>> Enter BEGIN HOMEBASE for Dialog Announcements <<<
        >>>   of new databases, price changes, etc.   <<<
                              ****
* * * ALL NEW CURRENT YEAR RANGES HAVE BEEN * * *
* * * INSTALLED   * * *
SYSTEM:HOME
Cost is in DialUnits
Menu System II: D2 version 1.7.9 term=ASCII
                        *** DIALOG HOMEBASE(SM) Main Menu ***

 Information:
   1. Announcements (new files, reloads, etc.)
   2. Database, Rates, & Command Descriptions
   3. Help in Choosing Databases for Your Topic
   4. Customer Services (telephone assistance, training, seminars, etc.)
   5. Product Descriptions

 Connections:
   6. DIALOG(R) Document Delivery
   7. Data Star(R)

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     /H = Help   /L = Logoff   /NOMENU = Command Mode

Enter an option number to view information or to connect to an online
 service. Enter a BEGIN command plus a file number to search a database
(e.g., B1 for ERIC).
?b 2,6,8,34,434,35,62,65,77,99,144,94,233,238,266,15,16,98,239,275,621,674,256,278,9,14
8,624,553,268,625,474,696

>>>   77 does not exist
>>>   238 does not exist
>>>   278 does not exist
>>>3 of the specified files are not available
        07jan04 14:25:22 User264815 Session D40.1
              $0.00   0.153 DialUnits FileHomeBase
      $0.00   Estimated cost FileHomeBase
      $0.46   TELNET
      $0.46   Estimated cost this search
      $0.46   Estimated total session cost   0.153 DialUnits

SYSTEM:OS   - DIALOG OneSearch
   File   2:INSPEC   1969-2003/Dec W2
          (c) 2003 Institution of Electrical Engineers
File   2: Alert feature enhanced for multiple files, duplicates
removal, customized scheduling. See HELP ALERT.
   File   6:NTIS   1964-2004/Jan W1
          (c) 2004 NTIS, Intl Cpyrght All Rights Res
   File   8:Ei Compendex(R)   1970-2004/Dec W4
          (c) 2004 Elsevier Eng. Info. Inc.
   File   34:SciSearch(R) Cited Ref Sci   1990-2003/Dec W4
          (c) 2003 Inst for Sci Info
File   34: New prices as of 1/1/2004 per Information Provider
request. See HELP RATES 34.
   File 434:SciSearch(R) Cited Ref Sci   1974-1989/Dec
          (c) 1998 Inst for Sci Info
File 434: New prices as of 1/1/2004 per Information Provider
request. See HELP RATES434.
   File 35:Dissertation Abs Online 1861-2003/Nov

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             (c) 2003 ProQuest Info&Learning
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   File   65:Inside Conferences  1993-2004/Jan W1
             (c) 2004 BLDSC all rts. reserv.
   File   99:Wilson Appl. Sci & Tech Abs  1983-2003/Nov
             (c) 2003 The HW Wilson Co.
   File  144:Pascal  1973-2003/Dec W2
             (c) 2003 INIST/CNRS
   File   94:JICST-EPlus  1985-2004/Dec W4
             (c)2004 Japan Science and Tech Corp(JST)
   File  233:Internet & Personal Comp. Abs.  1981-2003/Sep
             (c) 2003 EBSCO Pub.
   File  266:FEDRIP  2003/Nov
             Comp & dist by NTIS, Intl Copyright All Rights Res
   File   15:ABI/Inform(R)   1971-2004/Jan 07
             (c) 2004 ProQuest Info&Learning
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   File   16:Gale Group PROMT(R)   1990-2004/Jan 07
             (c) 2004 The Gale Group
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*File   16: Alert feature enhanced for multiple files, duplicate
removal, customized scheduling. See HELP ALERT.
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   File   98:General Sci Abs/Full-Text   1984-2003/Nov
             (c) 2003 The HW Wilson Co.
   File  239:Mathsci  1940-2003/Feb
             (c) 2003 American Mathematical Society
   File  275:Gale Group Computer DB(TM)   1983-2004/Jan 07
             (c) 2004 The Gale Group
   File  621:Gale Group New Prod.Annou.(R)   1985-2004/Jan 07
             (c) 2004 The Gale Group
   File  674:Computer News Fulltext  1989-2003/Dec W3
             (c) 2003 IDG Communications
   File  256:SoftBase:Reviews,Companies&Prods.  82-2003/Nov
             (c)2003 Info.Sources Inc
   File    9:Business & Industry(R)   Jul/1994-2003/Dec 29
             (c) 2003 Resp. DB Svcs.
   File  148:Gale Group Trade & Industry DB  1976-2004/Jan 07
             (c)2004 The Gale Group
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*File 148: Alert feature enhanced for multiple files, duplicate
removal, customized scheduling. See HELP ALERT.
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   File  624:McGraw-Hill Publications  1985-2004/Jan 07
             (c) 2004 McGraw-Hill Co. Inc
```
*File 624: Homeland Security & Defense and 9 Platt energy journals added
Please see HELP NEWS624 for more
```
   File  553:Wilson Bus. Abs. FullText  1982-2003/Nov
             (c) 2003 The HW Wilson Co
   File  268:Banking Info Source  1981-2004/Dec W4
             (c) 2004 ProQuest Info&Learning
```
*File 268: SELECT IMAGE AVAILABILITY FOR PROQUEST FILES
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   File  625:American Banker Publications  1981-2004/Jan 07
             (c) 2004 American Banker
   File  474:New York Times Abs  1969-2004/Jan 06
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             (c) 2004 The Dialog Corp.


     Set  Items  Description
     ---  -----  -----------
?s ASIC and (encrypt? or encipher? or cipher?) (s) (password or PIN or identifier or ke
y)
Processed  20 of  29 files ...
Processing
Completed processing all files
         92423  ASIC
        213615  ENCRYPT?
```

```
              1220  ENCIPHER?
             14602  CIPHER?
            130042  PASSWORD
            257963  PIN
             39365  IDENTIFIER
           3742227  KEY
             55428  ((ENCRYPT? OR ENCIPHER?) OR CIPHER?)(S)(((PASSWORD OR
                    PIN) OR IDENTIFIER) OR KEY)
      S1     439    ASIC AND (ENCRYPT? OR ENCIPHER? OR CIPHER?) (S) (PASSWORD
                    OR PIN OR IDENTIFIER OR KEY)
?s touchpad or touch (2n) pad or touch (2n) screen
              3909  TOUCHPAD
            458325  TOUCH
            126847  PAD
              4304  TOUCH(2N)PAD
            458325  TOUCH
            974770  SCREEN
             39458  TOUCH(2N)SCREEN
      S2    46785   TOUCHPAD OR TOUCH (2N) PAD OR TOUCH (2N) SCREEN
?s COG and ASIC
              9081  COG
             92423  ASIC
      S3        25  COG AND ASIC
?s tamper (2n) resistant
             24955  TAMPER
            570334  RESISTANT
      S4     4369   TAMPER (2N) RESISTANT
?s keypad or key(1n)pad (s) password? or PIN? or idnetifier? or secret or key?
>>>File 144 processing for PIN? stopped at PINSKER
>>>File 16 processing for PIN? stopped at PINPOINTEK
Processing
Processed  10 of  29 files ...
>>>File 148 processing for PIN? stopped at PINOCHET
Processing
Processed  20 of  29 files ...
Completed processing all files
             31925  KEYPAD
           3742227  KEY
            126847  PAD
            163522  PASSWORD?
                23  KEY(1N)PAD(S)PASSWORD?
           1171867  PIN?
                 0  IDNETIFIER?
            260196  SECRET
           4420520  KEY?
      S5 5592489    KEYPAD OR KEY(1N)PAD (S) PASSWORD? OR PIN? OR IDNETIFIER?
                    OR SECRET OR KEY?
?e au= lungaro,james

Ref    Items  Index-term
E1         0  *AU=LUNGARO,JAMES
E2         3   AU=LUNGARONI G
E3        24   AU=LUNGAROTTI F
E4        18   AU=LUNGAROTTI M S
E5        24   AU=LUNGAROTTI MS
E6         9   AU=LUNGAROTTI S
E7         1   AU=LUNGAROTTI, C.
E8         2   AU=LUNGAROTTI, M. S.
E9         2   AU=LUNGAROVA M
E10        1   AU=LUNGAROVA, M.
E11        1   AU=LUNGARZO C
E12        1   AU=LUNGARZO, CARLOS


        Enter P or PAGE for more
?e au= tso,susan

Ref    Items  Index-term
```

```
E1         0 *AU=TSO,SUSAN
E2         5  AU=TSOA E
E3         2  AU=TSOA R
E4         1  AU=TSOA RM
E5         3  AU=TSOA RW
E6         3  AU=TSOA, E.
E7         3  AU=TSOA, EUGENE
E8         1  AU=TSOA, EUGENE YU-SENG
E9         1  AU=TSOANAKIS O
E10        1  AU=TSOAR B
E11       43  AU=TSOAR H
E12        2  AU=TSOAR HAIM

          Enter P or PAGE for more
?e au=fernando,llavanya

Ref    Items  Index-term
E1         0 *AU=FERNANDO,LLAVANYA
E2         1  AU=FERNANDOCOELHESDASILVA J
E3         1  AU=FERNANDODAROCHA L
E4         1  AU=FERNANDODELCIAMPO, L.
E5         1  AU=FERNANDODONGAS MC
E6         1  AU=FERNANDOFUCK G
E7         1  AU=FERNANDOGILDAY C
E8         1  AU=FERNANDOGOTHARDO L
E9         1  AU=FERNANDOMEDRANO J
E10        1  AU=FERNANDOORTEGA C
E11        3  AU=FERNANDOPULE, N.
E12        1  AU=FERNANDOPULIE D

          Enter P or PAGE for more
?e au=lee,simon

Ref    Items  Index-term
E1         0 *AU=LEE,SIMON
E2         1  AU=LEE,T.
E3         1  AU=LEE,TIMOTHY
E4         1  AU=LEE,Y. -S.
E5         1  AU=LEE,Y. W.
E6         1  AU=LEE,YUANC
E7         3  AU=LEE,YUNG-CHANG
E8         1  AU=LEE', S.-H.
E9         1  AU=LEEA E J D
E10        1  AU=LEEA HAIWON
E11        1  AU=LEEA HEE-YONG
E12        1  AU=LEEA KYUNG-SUP

          Enter P or PAGE for more
?s chip (n) on (n) glass (n) technology
Processing
Processed  10 of  29 files ...
Processing
Processed  20 of  29 files ...
Completed processing all files
          898141  CHIP
        46634508  ON
         1127958  GLASS
         9217418  TECHNOLOGY
      S6     141  CHIP (N) ON (N) GLASS (N) TECHNOLOGY
?s LCD and s6
          136892  LCD
             141  S6
      S7      98  LCD AND S6
?s7 and ASIC
         8420585  7
           92423  ASIC
      S8   12627  7 AND ASIC
```

```
?'s s7 and ASIC
                98  S7
             92423  ASIC
      S9         2  S7 AND ASIC
```
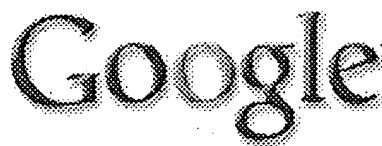
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[PDF] **Chip On Glass technology HDG1602P-2**
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... 65.0 10.8 (A /A) 15.7 (V/A) 19. 7 27. 7 15.1 1.8x13=23.4 4.8 5 2.0
2.1 MAX 10.6 1 14 3.15 2.0 **Chip** On **Glass technology** HDG1602P-2
www.hantronix.com/down/1602p-2.pdf - Similar pages

[PDF] **Chip On Glass technology HDG12864L-6**
File Format: PDF/Adobe Acrobat - View as HTML
... g Dimensional Drawing 128 X 64 Dots Graphic, LED Backlight
#Has built-in inverter
for negative power supply Power Supply **Chip** On **Glass technology**
HDG12864L-6 ...
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File Format: PDF/Adobe Acrobat - View as HTML
... inverter for negative power supply Power Supply V DD V 1 V 5 1.0uF x 5
CAP2+ CAP2-
CAP1+ CAP1- VOUT 5.0V + L C M 4.7uF x 3 **Chip** On **Glass technology**
HDG12864F-1
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[PDF] **Chip On Glass technology HDG12864F-3**
File Format: PDF/Adobe Acrobat - View as HTML
... built-in inverter for negative power supply Power Supply V DD V 5 V 1 1.0uF CAP2+
CAP2- CAP1- CAP1+ V OUT 5.0V L C M 2.2uF **Chip** On **Glass technology** HDG12864F-3 ...
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CBC News: Prototype computer chip-on-glass technology displayed
Prototype computer **chip**-on-**glass technology** displayed Last Updated Tue,
22 Oct 2002 18:05:10 TOKYO - A transparent computer processor ...
cbc.ca/stories/2002/10/22/sharp021022 - 19k - Cached - Similar pages

TFT LCDs Employ Chip-On-Glass Technology
Product Locator >> Components & Assemblies >> Displays & Indicators >> LCDs (includes
modules, panels, etc.) TFT LCDs Employ **Chip-On-Glass Technology** May 1999 ...
www.eepn.com/Locator/Products/ArticleID/ 17083/Action/Issue/17083.html - Similar pages

Character LCD Taps Chip-On-Glass Technology
... Locator >> Components & Assemblies >> Displays & Indicators >> LCDs (includes modules,
panels, etc.) Character LCD Taps **Chip-On-Glass Techn l gy** November 1999 ...
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New Technology Products - BD-Chip In Glass Displays with Built-in ...
... VFD), which find widespread use as easy-to-see display elements, now face new **technical**

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demands for ... has developed the BD series of **chip-in-glass** (CIG) vacuum ...
www.noritake-elec.com/bd_chip_in_glass_built-in.htm - 28k - Cached - Similar pages

Computing Canada: Seiko Instruments Vitrium displays use **Chip-On** ...
... Article. Seiko Instruments Vitrium displays use **Chip-On-Glass technology**.(the Vitrium
G8 liquid-crystal display)(Product Announcement)(Brief Article) Computing ...
www.findarticles.com/cf_dls/m0CGC/ n36_v24/21177433/p1/article.jhtml - 11k - Cached - Similar pages

Glass Technology Windshield Repair-Gainesville-Florida-1-352-213 ...
Save your Windshield and your money with rock **chip** repair. **Glass Technology** TM
Windshield Repair Company Gainesville, Florida. Since 1989. What do we do? ...
rogersunderland.com/glass_technology/ windshield_repair.html - 23k - Cached - Similar pages

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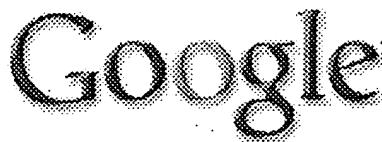
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... to ease the design-in process for engineers using Seiko Instruments'
Vitrium™
G4, a ¼ VGA LCD display developed using **Chip**-On-**Glass technology** for
optimal ...
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introduces the first off-the-shelf LCD displays developed using **Chip-On-Glass**
technology for optimal reliability, contrast and mechanical thinness.
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Design News + Product Design and Development - Chip-On-Glass comes ...
Seiko has introduced what it says are the first off-the-shelf
LCD displays developed using **Chip-On-Glass technology**. ...
www.manufacturing.net/dn/article/CA122229 - Similar pages

Introduction
... support from the Industry & **Technology** Development Council of the HKSAR Government
for the promotion and dissemination of **Chip On Glass Technology** to local ...
www.hkpc.org/hkpc/html/ div_coe_unit.asp?service=coe_aeptc&unit=4 - 4k - Cached - Similar pages

Tianma Microelectronics Chip-On-Glass (COG)
... Since the **Chip-On-Glass** integrated circuit has been invented by Epson, COG **technology**
became very popular due to the demand for more compact applications. ...
www.tianma.com/technologies/cog.htm - 18k - Cached - Similar pages

Noritake's Automation Excellence Award 2of3
... Advances in **Chip-in-Glass technology** provide VFD graphics modules increased function,
lower cost and a more compact design. Fig 1. Structural Schema of BD VFD. ...
www.noritake-elec.com/award2.htm - 7k - Cached - Similar pages
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ECN - Customized Chip on Glass LCD Modules
... functionality. Data Modul's advanced COG **technology** (**Chip** on **Glass**)
is particularly effective when designing custom-made modules. It ...
www.reedelectronicsgroup.com/esec/Article_212626.htm - Similar pages

nextek inc. manufacturing services for advanced technology, high ...
... 6 axis alignment, active alignment, advanced **technol** gy, alumina, analytical ... package,
ceramic, **chip** on board, **chip** on flex, **chip** on **glass**, **chip** scale package ...

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www.nextekinc.com/careerZ.html - 9k - Cached - Similar pages

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6 axis alignment, active alignment, advanced **technology**, alumina, analytical
laboratory ... **chip** on board, **chip** on flex, **chip** on **glass**, **chip** scale package ...
www.nextekinc.com/servicesZ.html - 8k - Cached - Similar pages
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Technology Review: **Chips** Go 3-D
... Mike Farmwald, cofounder of **chip** connection **technology** company Rambus, and others—starts
with a standard silicon **chip**. It paves the **chip** with **glass**, adds a ...
www.techreview.com/articles/innovation40102.asp - Similar pages

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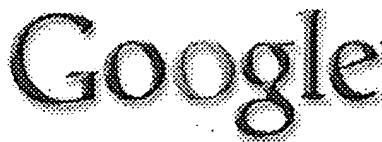
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... **Chip-On-Glass technology** eliminates the use of zebra ... for standard quad flat pack **chips**
or drivers ... Galaxy QuickForm Pulse Charge/Termination **technology** shows 30 ...
www.prweb.com/releases/1998/6/prweb4791.htm - 25k - Cached - Similar pages

[PDF] High-Sensitivity Smart Sensors Based on Thin-Film on ASIC ...

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... CSEM, high-efficiency APS in TFA **technology** are currently ... been deposited on chromium-coated
glass sub- strates ... far been carried out on a **chip** (BIOCHIP) designed ...
www.csem.ch/corporate/Report2002/pdf/p42.pdf - Similar pages

New Technology Products - CL-Active Matrix Displays

... matrixes are fabricated and arranged on the **glass** plate ... This **technology** reduces the
number of lead wires pulled ... diagram of the inside of a **chip**.) The interface ...
www.noritake-elec.com/cl_active_matrix_displays.htm - 33k - Cached - Similar pages

[PDF] ASIC Packaging

File Format: PDF/Adobe Acrobat - View as HTML
... Inside its Flip-**chip** BGA packages, Fujitsu's unique wiring strip interconnect ... Key features of Fujitsu's FC-BGA **technology** are: • **Glass** Ceramics or ...
www.fma.fujitsu.com/pdf/ASIC%20PKG.pdf - Similar pages

JAPAN IMC/IEMT April 1998 HighLights

... CSP. The 64M DRAM **chip** was connected to the **glass** ceramic substrate via
Au bumps by flip **chip** bonding **technique**. "Reliability ...
www.ewh.ieee.org/soc/cpmt/newsletter/ 199806/JapIMCF.html - 9k - Cached - Similar pages

Appendix 1-B - Canadian Industry Sector Technology Interests

... example, flip-**chip**, **chip-on-glass**, **chip**-on-board ... **chip**, board and product design services
for telecommunication ... RF, digital and mixed-signal **technology** for radar ...
www.cmc.ca/about/corporation/ plan/Module1/appendix1b.html - 6k - Cached - Similar pages

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... It is covered with epoxy. Top. **Chip-on-Glass** (COG) is a new **techn logy** that mounts
the LCD driver to the contact edge of the LCD **glass**. Top. ...
www.amulettechnologies.com/glossary.html - 27k - Cached - Similar pages

Skyline Sales & Associates, Inc.

... EDT has a full range of LCD products that features STN and FSTN **technology** with

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COB (**chip** on board) COF (**chip** on flex), COG (**chip** on **glass**), TAB (tape ...
www.skylinesalesassoc.com/skyline_lines.html - 19k - Cached - Similar pages

Electronic News: Amkor Gains LSI Logic Know-How.(Amkor **Technology** ...
... to make its organic laminate flip **chip technology** an industry ... for various system-on-a-**chip**
and other designs, competing against **glass** ceramic materials ...
www.findarticles.com/cf_dls/m0EKF/ 2249_44/53510616/p1/article.jhtml - 13k - Cached - Similar pages

EM Microelectronic, low power ICs, RFID, microcontroller, ultra ...
... Assembly **technologies** - COB, **Chip**-on-Board **technology** - COG, **Chip**-on-**Glass technology**
- COF, **Chip**-on-Film **technology** - With integrated back-light or front ...
www.emmarin.com/Line.asp?IdLine=30 - 29k - Cached - Similar pages

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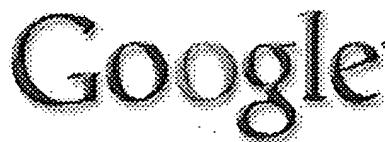
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EM Microelectronic, low power ICs, RFID, microcontroller, ultra ...

... using a variety of different **LCD** and assembly **technologies**. Assembly **technologies**
- COB, **Chip**-on-Board **technology** - COG, **Chip**-on-**Glass technology** -
COF, **Chip**-on ...
www.emmarin.com/Line.asp?IdLine=30 -- 29k - Cached - Similar pages

EM Microelectronic, low power ICs, RFID, microcontroller, ultra ...

... EM's **LCD** drivers ICs often require no external component and can be used
with **Chip**-On-**Glass**, **Chip**-on-Flex, **Chip** on Board or TAB **technologies**. ...
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UV Cured Adhesives, LEDs, LCD Displays, PCB Design, Crystals ...

... Modular Kit Enclosed Shaft Employing phased-array **ASIC technology** Resolutions up
to ... Type TAB (Tape Automated Bonding) & COG (**Chip** on **Glass** Character Type) ...
www.prorepco.com/ - 19k - Cached - Similar pages

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... Design and manufacture a broad selection of **LCD** and LCM **technologies** including
"**chip on glass**" and "**chip on film**" to meet customer ...
Description: Manufacturers' representative of optical network **and** connectivity, synchronisation **and** timing products,...
Category: Business > Electronics and Electrical > ...
www.logic1sales.com/ - 19k - Cached - Similar pages

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... TAB bonding **techn logy** can be widely use on different application such as (1) Soft
mechanical device : **LCD** Module ... A: COG stand for **Chip**-on-**Glass**, it use ACF ...
portal-ap.picvue.com.tw/picvue/english/FAQ.htm -- 36k -- Cached - Similar pages

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SMaL Technology
... Kit uses SMaL's proprietary Autobrite wide dynamic range **technology** which adapts ... Timing and Control, On-**chip**. ... Lens, 4-element **glass**, focal length = 7 mm, F/3.2 ...
www.smalcamera.com/up3lcd.html - 14k - Cached - Similar pages

Yahoo! Directory Semiconductor Makers
... in the form of compact hybrid **glass** circuits on ... supplier of custom communication **chips** for the ... Sitronix **Technology** Corporation [SPONSOR] - design house for **LCD** ...
dir.yahoo.com/.../Business_to_Business/Electronics/ Board_Level_Components/Semiconductors/Makers/ - 32k - Cached - Similar pages

Elatec - EM Marin
... Voltage bias and mux signal generated on **chip**; 8 x 60 ... industry standard of 2 x 1.1mm **glass**, which is ... analog designs with Mixed Mode Array **technology** for medium ...
www.elateceurope.com/emmarin/ - 30k - Cached - Similar pages

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